



MEG-02-015

Ser. No. 10/685,872

November 9, 2005

To: Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

Fr: Stephen B. Ackerman, Reg. No. 37,761  
28 Davis Avenue  
Poughkeepsie, N.Y. 12603

Subject:

Serial No.	10/685,872	10/15/03
M.S. LIN		
"POST PASSIVATION INTERCONNECTION SCHEMES ON TOP OF THE IC CHIPS"		
Group Art Unit: 2822	KEVIN M. PICARDAT	

#### RESPONSE TO OFFICE ACTION

Dear Sir:

In response to the Office Action dated September 9, 2005, please amend the above-identified application for patent as follows:


#### CERTIFICATE OF MAILING

I hereby certify that this correspondence is being deposited with the United States Postal Service as first class mail in an envelope addressed to: Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450, on November 9, 2005.

Stephen B. Ackerman, Reg. No. 37,761

Signature

Date

  
11/9/05

Amendments to the Specification begin on page 3 of this paper.

Remarks/Arguments begin on page 4 of this paper.